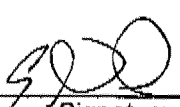


**RECORDATION FORM COVER SHEET
PATENTS ONLY**

To the Director, U.S. Patent and Trademark Office: Please record the attached original documents or copy thereof.

1. Name of conveying party: Linda S. Irish Additional name(s) of conveying party(ies) attached? () Yes (X) No	2. Name and address of receiving party: Name: QUALCOMM Incorporated Street Address: 5775 Morehouse Drive City: San Diego State: CA ZIP: 92121-1714 Additional name(s) of receiving party(ies) attached? () Yes (X) No
3. Nature of conveyance: (X) Assignment () Security Agreement () Merger () Change of Name () Other: Execution Date: April 17, 2012	4. US Application number: (X) Patent Application No.: 13/455910 Filing Date: April 25, 2012 Additional numbers attached? () Yes (X) No
5. Party to whom correspondence concerning document should be mailed: Customer No. 14,870 Address: Knobbe, Martens, Olson & Bear, LLP 2040 Main Street, 14 th Floor Irvine, CA 92614 Return Fax: (949) 760-9502 Attorney's Docket No.: QPC.156A / 120461	6. Total number of applications and patents involved: 1
7. Total fee (37 CFR 1.21(h)): \$40 (X) Authorized to be charged to deposit account	8. Deposit account number: 11-1410 Please charge this account for any additional fees which may be required, or credit any overpayment to this account.
9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct, and any attached copy is a true copy of the original document. <u>Eric M. Nelson</u> Name of Person Signing 43,829 Registration No.  _____ Signature <u>5/11/2012</u> _____ Date Total number of pages including cover sheet, attachments and document: 3	

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ASSIGNMENT

WHEREAS, I, **Linda S. Irish**, a citizen of **United States of America**, having a mailing address located at **5775 Morehouse Drive San Diego, CA 92121**; and a resident of **San Diego, CA**, have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **SYSTEMS, METHODS, AND APPARATUS FOR A HIGH POWER FACTOR SINGLE PHASE RECTIFIER** (collectively the "**INVENTIONS**") for which I have executed and/or may execute one or more patent applications therefor; and

WHEREAS, **QUALCOMM Incorporated** (hereinafter "**ASSIGNEE**"), a Delaware corporation, having a place of business at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**, desires to acquire or otherwise obtain the entire right, title, and interest in and to said **INVENTIONS**, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I do hereby acknowledge that I have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto **ASSIGNEE**, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said **INVENTIONS**, including all patent applications therefor that may have been filed or may be filed hereafter for said **INVENTIONS** in the United States, including but not limited to U.S. Application No(s). 13455910 filed 4.25.2012 Qualcomm Reference No. **120461**, and all provisional applications relating thereto, together with U.S. Provisional Application No(s). **61/561,184**, filed **November 17, 2011**, Qualcomm Reference No. **120461P1**, (and do hereby authorize **ASSIGNEE** and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND I further do acknowledge and agree that I have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto **ASSIGNEE**, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said **INVENTIONS**, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said **INVENTIONS** in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said **INVENTIONS** in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND I DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND I DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which I may be entitled, or that I may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND I HEREBY covenant and agree that I will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to me respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND I HEREBY represent that I have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that I have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at San Diego, CA, on April 17, 2012 Linda S. Irish
LOCATION DATE